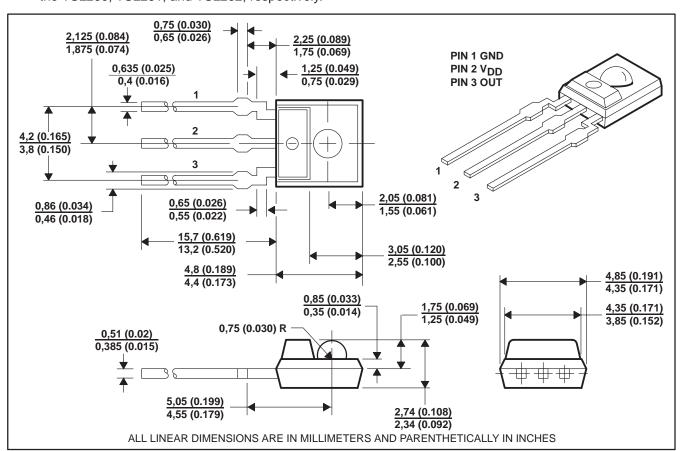
- Integral Visible Light Cutoff Filter
- Monolithic Silicon IC Containing Photodiode, Operational Amplifier, and Feedback Components
- Converts Light Intensity to Output Voltage
- High Irradiance Responsivity Typically
 42 mV/(μW/cm²) at λ_p = 940 nm (TSL260)
- Low Dark (Offset) Voltage . . . 10 mV Max at 25°C, V_{DD} = 5 V
- Single-Supply Operation
- Wide Supply Voltage Range . . . 3 V to 9 V
- Low Supply Current . . . 800 μA Typical at V_{DD} = 5 V
- Advanced LinCMOS™ Technology

description

The TSL260, TSL261, and TSL262 are light-to-voltage optical sensors each combining a photodiode and a transimpedance amplifier (feedback resistor = 16 M Ω , 8 M Ω , and 2 M Ω , respectively) on a single monolithic integrated circuit. The output voltage is directly proportional to the infrared light intensity (irradiance) on the photodiode. The TSL260, TSL261, and TSL262 utilize Texas Instruments silicon-gate LinCMOSTM technology, which provides good amplifier offset-voltage stability and low power consumption.

mechanical data

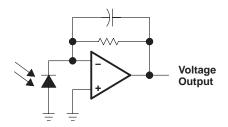
The photodiode/amplifier chip is packaged in a black, infrared-transmissive plastic package. The integrated photodiode active area is typically 1,0 mm² (0.0016 in²), 0.5 mm² (0.00078 in²), and 0.26 mm² (0.0004 in²) for the TSL260, TSL261, and TSL262, respectively.



LinCMOS is a trademark of Texas Instruments Incorporated.



functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{DD} (see Note 1)	10 V
Output current, IO	±10 mA
Duration of short-circuit current at (or below) 25°C (see Note 2) .	5 s
Operating free-air temperature range, T _A	–25°C to 85°C
Storage temperature range	–25°C to 85°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	240°C

NOTES: 1. All voltages are with respect to GND.

2. Output may be shorted to either supply.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	3	5	9	V
Operating free-air temperature, TA	0		70	°C

electrical characteristics at V_DD = 5 V, T_A = 25°C, λp = 940 nm, R_L = 10 k Ω (unless otherwise noted) (see Note 3)

		TEST	TSL260			TSL261			TSL262				
	PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
VDARK	Dark voltage	$E_e = 0$		3	10		3	10		3	10	mV	
Vом	Maximum output	$E_e = 2.6 \text{ mW/cm}^2$	3.1	3.5		3.1	3.5		3.1	3.5		V	
		$E_e = 48 \mu\text{W/cm}^2$	1	2	3								
VO	Output voltage	$E_e = 87 \mu\text{W/cm}^2$				1	2	3				V	
		$E_e = 525 \mu \text{W/cm}^2$							1	2	3		
	Temperature coefficient of output voltage (VO)	$E_e = 48 \mu W/cm^2$, $T_A = 0^{\circ}C \text{ to } 70^{\circ}C$		±1									
		$E_e = 87 \mu W/cm^2$, $T_A = 0^{\circ}C \text{ to } 70^{\circ}C$					±1					mV/°C	
		$E_e = 525 \mu\text{W/cm}^2$, $T_A = 0^{\circ}\text{C} \text{ to } 70^{\circ}\text{C}$								±1			
N _e	Irradiance responsivity	See Note 4		42			23			3.8		mV/(μW/cm ²)	
	Supply current	$E_e = 48 \mu W/cm^2$, No load		900	1600								
I _{DD}		$E_e = 87 \mu W/cm^2$, No load					900	1600				μΑ	
		$E_e = 525 \mu\text{W/cm}^2$, No load								900	1600		

NOTES: 3. The input irradiance E_e is supplied by a GaAs infrared-emitting diode with λ_p = 940 nm.

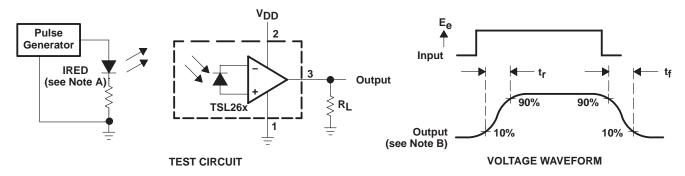
4. Irradiance responsivity is characterized over the range $V_O = 0.05$ to 3 V.



operating characteristics at T_A = 25°C (see Figure 1)

DADAMETED		TEST COMPITIONS	TSL260			٦	ΓSL261		TSL262			LINUT
	PARAMETER	TEST CONDITIONS	MIN	MIN TYP M		MIN	TYP	MAX	MIN	TYP MAX		UNIT
t _r	Output pulse rise time	$V_{DD} = 5 \text{ V}, \lambda_p = 940 \text{ nm}$		360			90			7		μs
tf	Output pulse fall time	$V_{DD} = 5 \text{ V}, \lambda_p = 940 \text{ nm}$		360			90			7		μs
Vn	Output noise voltage	$V_{DD} = 5 \text{ V}, f = 20 \text{ Hz}$		0.6			0.5			0.4		μV/√ Hz

PARAMETER MEASUREMENT INFORMATION

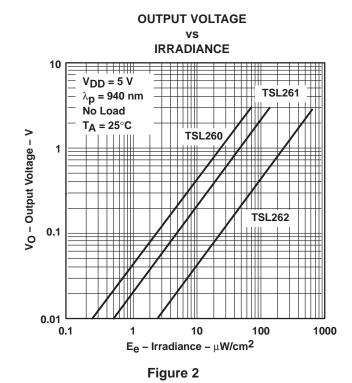


NOTES: A. The input irradiance is supplied by a pulsed GaAs infrared-emitting diode with the following characteristics: $\lambda_p = 940$ nm, $t_f < 1$ μs , $t_f < 1$ μs .

B. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r < 100$ ns, $Z_i \ge 1$ MHz, $C_i \le 20$ pF.

Figure 1. Switching Times

TYPICAL CHARACTERISTICS



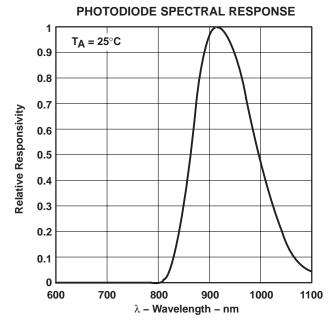
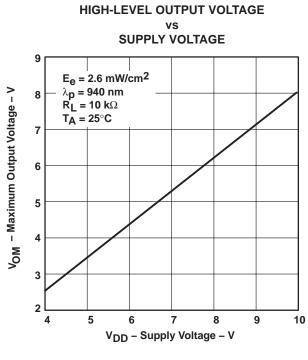


Figure 3

TEXAS VI

TYPICAL CHARACTERISTICS



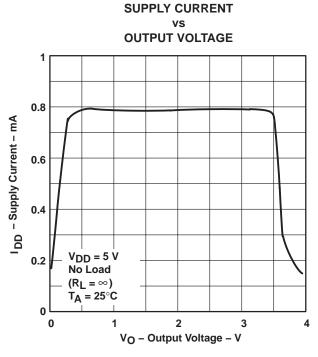


Figure 4

Figure 5

NORMALIZED OUTPUT VOLTAGE

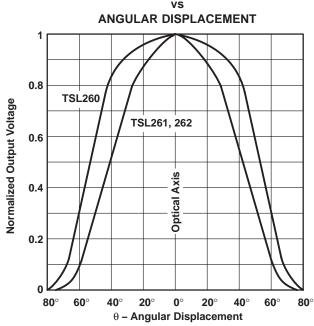
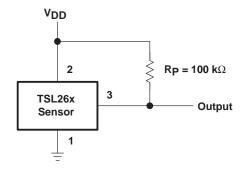


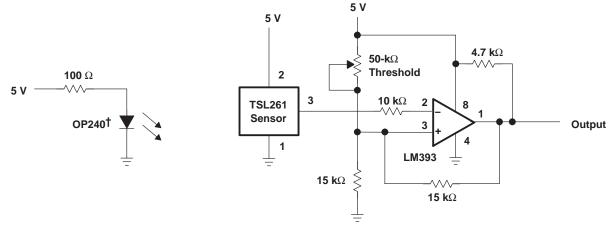
Figure 6





NOTE A: Pullup resistor extends linear output range to near V_{DD} with minimal (several millivolts typical) effect on V_{DARK}; particularly useful at low V_{DD} (3 V to 5 V).

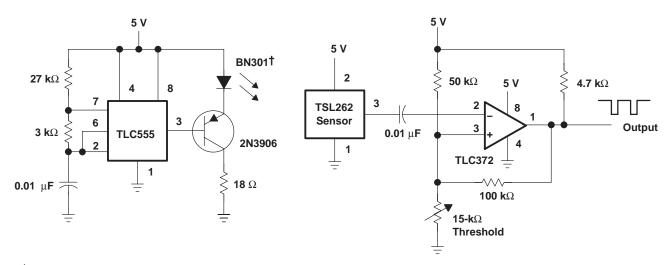
Figure 7. Pullup for Increased VOM



† OPTEK part number

NOTE A: Output goes high when beam is interrupted; working distance is several inches or less. Intended for use as optical-interrupter switch or reflective-object sensor.

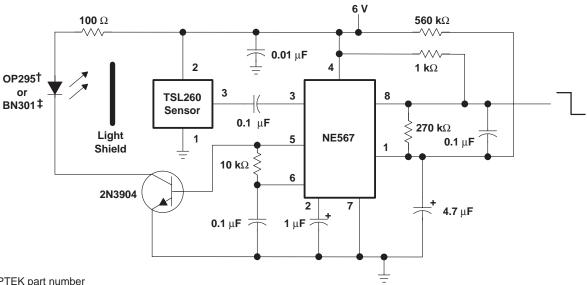
Figure 8. Short-Range Optical Switch With Hysteresis



†Stanley part number

NOTE A: Output pulses low until beam is interrupted. Useful range is 1 ft to 20 ft; can be extended with lenses. This configuration is suited for object detection, safety guards, security systems, and automatic doors.

Figure 9. Pulsed Optical-Beam Interrupter

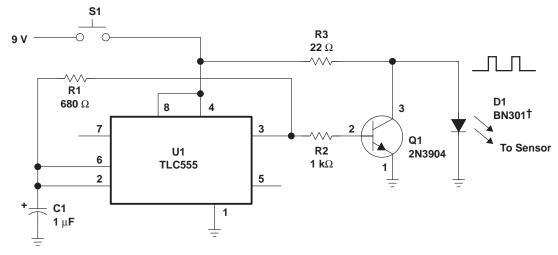


[†] OPTEK part number

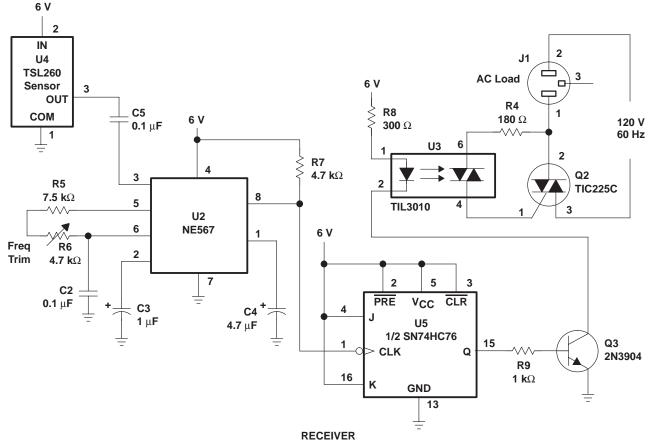
NOTE A: Output goes low when light pulses from emitter are reflected back to sensor. Range is 6 in to 18 in depending upon object reflectance. Useful for automatic doors, annunciators, object avoidance in robotics, automatic faucets, and security systems.

Figure 10. Proximity Detector

[‡]Stanley part number



TRANSMITTER

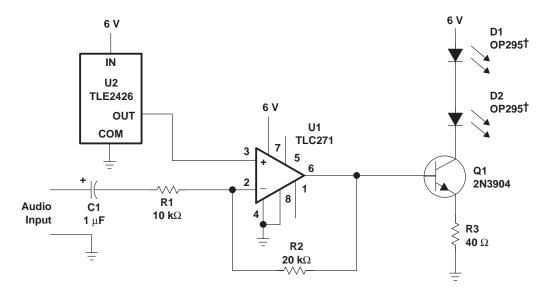


† OPTEK part number

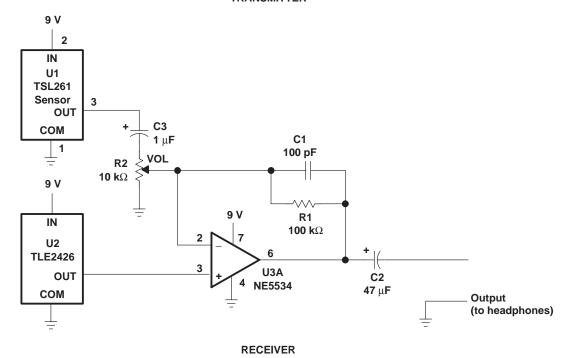
NOTE A: Single-channel remote control can be used to switch logic or light dc loads by way of U5 or ac loads by way of the optocoupler and triac as shown. Applications include ceiling fans, lamps, electric heaters, etc.

Figure 11. IR Remote Control





TRANSMITTER



† OPTEK part number

NOTE A: Simple transmission of audio signal over short distances (<10 ft). Applications include wireless headphones, wireless-telephone headset, and wireless-headset intercom.

Figure 12. IR Voice-Band Audio Link





PACKAGE OPTION ADDENDUM

2-Mar-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TSL260	OBSOLETE	TO	LL	3	TBD	Call TI	Call TI
TSL261	OBSOLETE	TO	LL	3	TBD	Call TI	Call TI
TSL262	OBSOLETE	TO	LL	3	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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